

G363-SR0-LAX4

HPC/AI Server - 3U DP NVIDIA HGX™ H200 4-GPU



Features

- Liquid-cooled NVIDIA HGX™ H200 4-GPU
- CPU+GPU direct liquid cooling solution
- 4th-generation NVIDIA® NVLink® 900GB/s
- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 16 x DIMMs
- Dual ROM Architecture
- 2 x 10Gb/s LAN ports via Broadcom® BCM57416
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 8 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swap bays
- 1 x M.2 slot with PCIe Gen4 x4 interface
- 6 x LP PCIe Gen5 x16 slots
- 2+1 3000W 80 PLUS Titanium redundant power supplies

Specification

Dimensions	3U (W448 x H130 x D800 mm)	I/O ports	Front: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN (default) Rear: 2 x RJ45
Motherboard	MS63-HD2	TPM	1 x TPM header with SPI interface (Optional TPM2.0 kit: CTM010)
CPU	5th/4th Gen Intel® Xeon® Scalable Processors Intel®Xeon® CPU Max Series Dual processor, LGA 4677 (Socket E) TDP up to 385W	Backplane Board	Speed and bandwidth: PCIe Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
Chipset	Intel® C741	Power Supply	2+1 3000W 80 PLUS Titanium redundant power supplies AC Input: 115-240V *The system power supply requires C19 power cord.
Memory	8-Channel DDR5 RDIMM, 16 x DIMMs 5th Gen Intel Xeon: Up to 5600 MT/s 4th Gen Intel Xeon & Intel Xeon Max Series: Up to 4800 MT/s	System Management	ASPEED® AST2600 Baseboard Management Controller GIGABYTE Management Console web interface
LAN	Front: 2 x 1Gb/s LAN (1 x Intel® I350-AM2) - Support NCSI function 1 x 10/100/1000 management LAN Rear: 2 x 10Gb/s LAN (1 x Broadcom® BCM57416)	OS Support	Windows Server, Red Hat Enterprise Linux server, Ubuntu, SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor
Video	Integrated in ASPEED® AST2600 - 1 x VGA port	System Fans	4 x 80x80x80mm (17,000rpm)
Storage	Front hot-swap: 8 x 2.5" Gen5 NVMe/SATA/SAS-4 *SAS card is required to support SAS drives. Internal M.2: 1 x M.2 (2280/22110), PCIe Gen4 x4	Operating Properties	Operating temperature: 10°C to 40°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
RAID	Intel® SATA RAID 0/1/10/5 Support optional RAID add-in cards	Packaging Content	1 x G363-SR0-LAX4, 1 x CoolIT CPU cold plate loop, 6 x Carriers, 1 x Mini-DP to D-Sub cable, 1 x L-shape Rail kit Packaging Dimensions: 1176 x 782 x 295 mm
Modular GPU	Liquid-cooled NVIDIA HGX™ H200 with 4 x SXM GPUs	Part Numbers	Barebone w/ NVIDIA module: 6NG363SR0DR000LBX4* Optional parts: - C19 power cord 125V/15A (US): 25CP1-018000-Q0R - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R - RMA packaging: 6NG363SR0SR-RMA-L100
Expansion Slots	Front: 2 x LP PCIe Gen5 x16 slots Rear: 4 x LP PCIe Gen5 x16 slots (with PCIe switches, support RDMA)		



Learn more at <https://www.GIGABYTE.com/enterprise>

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